

UHMWPE POROUS MATERIAL

SUNMAP LC-T5320

Features

- As SUNMAP is a porous sintered material having an open-cell structure; it offers the excellent air and moisture permeability.
- As SUNMAP is made of porous UHMWPE having high wear resistance and low friction coefficient the slip properties of SUNMAP is enhanced.
- SUNMAP offers good chemical resistance against typical acids and alkalis.
- Antistatic
- Flat surface (single side)

Structure

LC-T5320  ← Ultrahigh-molecular-weight Polyethylene Porous Film

Fig. 1

Properties

Table 1. General Properties

Item	Unit	Characteristic value				Test method
		0.2	0.3	0.5	1.0	
Thickness	mm	0.2	0.3	0.5	1.0	—
Air permeability	cm ³ /cm ² /sec	7.5	6.5	1.2	0.4	JIS L1096
Pore size	μm	17				—
Porosity	%	30				—
Tensile strength	MPa	12				JIS C2107
Elongation	%	90				JIS C2107
Hardness	Shore D	48				ASTM D2240
Surface Roughness (Ra)	μm	1.2 (Flat surface side)				JIS B 0601
Coefficient of kinetic friction	—	0.1				JIS K7125
Surface resistance	Ω/□	1×10 ¹⁰				JIS K7194

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LC-T5320_03E
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Product size

Table 2 Sheet type

Thickness (mm)	Width (mm)	Length (mm)
0.2	100~500	100~500
0.3		
0.5		
1.0		

Applications

- In ceramic condenser manufacturing process, SUNMAP is used as “shock-absorber”.
- In LCD manufacturing process, SUNMAP is used as “shock-absorber”.

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